L Number	Hits	Search Text	DB	Time stamp
69	2572	(257/668,669,674,738).CCLS.	USPAT; US-PGPUB	2004/09/13 11:13
-	3	(JP-11307586-$ or JP-11204720-$ or JP-05251616-$).did.	DERWENT	2004/09/12 10:30
-	4	(("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.	USPAT; US-PGPUB	2004/09/12 10:57
-	1	((("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.) and groove	USPAT; US-PGPUB	2004/09/12 10:33
-	0	(((("20040070053") or ("6352879") or ("6100594") or ("6229217")).PN.) and groove) and (11-307586 or 11-204720 or 05-251616 or 5-251616)	USPAT; US-PGPUB	2004/09/12 10:33
-	6878	(bend bending bended) and silicon and (groove trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/12 11:07
-	3734	(bend bending bended) and silicon and (groove trench) and (bond bonded bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/12 11:08
-	1399	((bend bending bended) and silicon and (groove trench) and (bond bonded bonding)) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/12 11:08
-	94	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/12 12:24
-	289	(bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/12 11:08
-	195	((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) not (((bend bending bended) near4 stress and silicon and (groove trench) and (bond bonded bonding)) and ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/12 13:24
-	2	"4984063"	USPAT; US-PGPUB	2004/09/12 14:49
-	19	"3860949"	USPAT; US-PGPUB	2004/09/12 14:53
-	13	"3860949" and silicon	USPAT; US-PGPUB	2004/09/12 14:53